

# VAC645 / 665

Leading in Vapor Phase Technology

Premium Vacuum Vapor Phase Soldering Machine For Highest Soldering Quality

**IBL**



## The Machine

The VAC645 / 665 reflow vapor phase soldering systems (available as batch or inline) are perfect for maximum solder quality and void-free soldering. The combination of the vapor phase soldering with a vacuum process significantly increases the reliability of the finished product. The soldering system operates in a complete inert atmosphere throughout the entire reflow and vacuum process. Many patented features are available and provide a wide range of flexibility.

## Overview

- 2 machine types for different board sizes
- Integrated flexible vacuum system
- Oxygen free soldering
- No overheating of components
- Low power consumption
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## Standard Equipment / Specification

- Comfortable operation with Touch Screen
- Automatic carrier in- and output
- Program memory up to 50 programs
- Wide variety of adjustable solder profiles
- Low fluid consumption with 2-chamber design and fluid recovery
- Integrated cooling fan for board cooling
- Minimum maintenance and wear due to „cool handling“ (all moving parts outside the process chamber)
- 4 internal channels for comfortable temperature measuring and profiling
- Energy management system
- Fluid level check
- Automatic liquid filtering

## Special features

- Vacuum process in the vapor phase for void-free soldering (**patented**)
- Automatic monitoring of vacuum pressure
- IPS, Intelligent Profiling System incl.
  - Soft Vapor Temperature Control (SVTC), temperature regulated profiles
  - Pilot Mode, set-up and profiling in one step
- Lead-free and leaded soldering with one fluid only, with different maximum temperatures
- Built-in software profiling capability
- Syncro-Mode
- Maintenance-free transport system (**patented**)
- Easy access to process chamber

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## Options

- RCS Rapid cooling system (**patented**)
- IR heater system (**patented**)
- VP-Control for convenient documentation and fine adjustment of the process
- Integrated PC-System
- Barcode-system for automatic program-change, traceability and unlimited program storage
- Measurement channels for board temperature recording
- Multi-Level-Mode for easy changeover between different solder heights
- Anti Fog System (AFS) for clear vision of the soldering process (**patented**)
- Adapter for double sided PCB boards
- UPS, uninterruptible power supply
- Inline-handling
- Closed-loop-chiller



Technical Data	VAC645	VAC665
Length (Inline)	2400 mm (3040 mm)	2810 mm (3450 mm)
Depth	1355 mm (2040 mm)	1355 mm (2040 mm)
Height	1420 mm	1420 mm
Weight	1030 kg (1290 kg)	1200 kg (1450 kg)
Loading/unloading level, approx.	950 mm	950 mm
Max. board size (manual loading / Batch)	635 x 440 x 70 mm	635 x 640 x 70 mm
Max. board size (Inline)	635 x 400 x 50 mm	635 x 400 x 50 mm
Liquid agent filling	40 kg	60 kg
Water connection	½" / 2,5-5 bar / 5l/min	½" / 2,5-5 bar / 6l/min
Max. heating capacity of Vapor Phase heater	10,4 kW / 8 kW	13 kW / 8 kW
Ø power consumption/h	5,5 kW/h (5,7 kW/h)	4,8 kW/h (5,8 kW/h)
Power supply	400/230 VAC, 12 kW (15kW)	400/230 VAC, 14 kW (19 kW)
Main fuse	32A, Typ "gL" or "C"	32A, Typ "gL" or "C"
External vacuum module LxDxH, weight	900 x 540 x 1100 mm, 90 kg	900 x 540 x 1100 mm, 90 kg

- Technical changes reserved

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